

UCC2913 UCC3913

SLUS274A – JANUARY 1999 – REVISED APRIL 2003



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾	PART NUMBER
-40°C to 85°C	PDIP (N)	UCC2913N
	SOIC (D)	UCC2913D
-0°C to 70°C	PDIP (N)	UCC3913N
	SOIC (D)	UCC3913D

(1) The N and D packaged are also available taped and reeled.
Add an R suffix to the device type (i.e., UCC2913NR).

ABSOLUTE MAXIMUM RATINGS

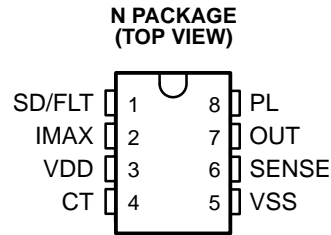
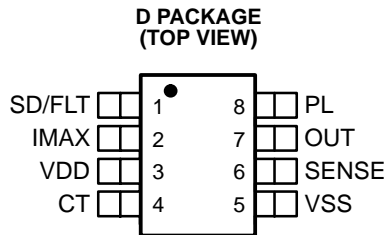
over operating free-air temperature range unless otherwise noted⁽¹⁾

		UCC2923 UCC3913	UNIT
Input voltage	IMAX	limited to VDD	V
Input current	VDD	50	mA
	SHUTDOWN	10	
	PL	10	
Operating junction temperature range, T _J		-55 to 150	°C
Storage temperature, T _{stg}		-65 to 150	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds		300	

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. All voltages are with respect to VSS (the most negative voltage). All currents are positive into and negative out of the specified terminal.

RECOMMENDED OPERATING CONDITIONS

	MIN	NOM	MAX	UNIT
Input current, I _{VDD}	2	5	20	mA



ELECTRICAL CHARACTERISTICS

$T_A = -40^{\circ}\text{C}$ to 85°C for UCC2913, $T_A = 0^{\circ}\text{C}$ to 70°C for UCC3913, $T_J = T_A$, $I_{VDD} = 2\text{ mA}$, $C_T = 4.7\text{ pF}$, $T_A = T_J$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT SUPPLY					
Minimum input current, VDD			1	2	mA
Regulator voltage	$2\text{ mA} \leq I_{SOURCE} \leq 10\text{ mA}$	8.5	9.5	10.5	V
Undervoltage lockout off-voltage		6	7	8	
FAULT TIMING					
Overcurrent threshold voltage	$T_J = 25^{\circ}\text{C}$	47.5	50.0	53.0	mV
	Over temperature	46.0	50.0	53.5	
Overcurrent input bias			50	500	nA
Timing capacitance charge current	$V_{CT} = 1.0\text{ V}$, $I_{PL} = 0\text{ A}$	-22	-36	-50	μA
	Overload condition, $V_{SENSE} - V_{IMAX} = 300\text{ mV}$	-0.7	-1.2	-1.7	mA
Timing capacitance discharge current	$V_{CT} = 1.0\text{ V}$, $I_{PL} = 0\text{ A}$	0.6	1.0	1.5	μA
Timing capacitance fault threshold voltage		2.2	2.4	2.6	V
Timing capacitance reset threshold voltage		0.32	0.50	0.62	V
Output duty cycle	Fault condition, $I_{PL} = 0\text{ A}$	1.7%	2.7%	3.7%	
OUTPUT					
High-level output voltage	$I_{OUT} = 0\text{ A}$	8.5	10		V
	$I_{OUT} = -1\text{ A}$	6	8		
Low-level output voltage	$I_{OUT} = 0\text{ A}$, $V_{SENSE} - V_{IMAX} = 100\text{ mV}$			0.01	
	$I_{OUT} = 2\text{ A}$, $V_{SENSE} - V_{IMAX} = 100\text{ mV}$		0.2	0.6	
LINEAR AMPLIFIER					
Sense control voltage	$V_{IMAX} = 100\text{ mV}$	85	100	115	mV
	$V_{IMAX} = 400\text{ mV}$	370	400	430	
Input bias			50	500	nA
SHUTDOWN/FAULT					
Shutdown threshold voltage		1.4	1.7	2.0	V
Input current	$V_{SD/FLT} = 5\text{ V}$	15	25	45	μA
High-level output voltage		6.0	7.5	9.0	V
Low-level output voltage				0.01	
Delay-to-output time			150	300	ns
POWER LIMITING					
PL regulator voltage	$I_{PL} = 64\text{ }\mu\text{A}$	4.35	4.85	5.35	V
Duty cycle control	$I_{PL} = 64\text{ }\mu\text{A}$	0.6%	1.2%	1.7%	
	$I_{PL} = 1\text{ mA}$	0.045%	0.1%	0.17%	
OVERLOAD					
Delay-to-output time			300	500	ns
Output sink current	$V_{SENSE} - V_{IMAX} = 300\text{ mV}$	40	100		mA
Overload threshold voltage	Relative to I_{IMAX}	140	200	260	mV

TERMINAL FUNCTIONS

TERMINAL NAME	NO.	I/O	DESCRIPTION
CT	4	I	A capacitor is connected to this pin in order to set the maximum fault time.
IMAX	2	I	This pin programs the maximum allowable sourcing current.
OUT	7	O	Output drive to the MOSFET pass element.
PL	8	I	This feature ensures that the average MOSFET power dissipation is controlled.
SENSE	6	I	Input voltage from the current sense resistor.
SD/FLT	1	O	This pin provides fault output indication and shutdown control.
VDD	3	O	Current driven with a resistor to a voltage at least 10V more positive than VSS.
VSS	5	O	Ground reference for the device and the most negative voltage available.

DETAILED PIN DESCRIPTIONS

CT

A capacitor connected to this pin allows setting of the maximum fault time. The maximum fault time must be more than the time to charge external load capacitance. The maximum fault time is defined as:

$$t_{\text{FAULT}} = \frac{(2 \times C_T)}{I_{\text{CH}}} \tag{1}$$

where

$$I_{\text{CH}} = 36 \mu\text{A} + I_{\text{PL}} \tag{2}$$

and I_{PL} is the current into the power limit pin. Once the fault time is reached the output shuts down for a time given by:

$$t_{\text{SD}} = 2 \times 10^6 \times C_T \tag{3}$$

IMAX

This pin programs the maximum allowable sourcing current. Since V_{DD} is a regulated voltage, a voltage divider can be derived from V_{DD} to generate the program level for the IMAX pin. The current level at which the output appears as a current source is equal to the voltage on the IMAX pin over the current sense resistor. If desired, a controlled current startup can be programmed with a capacitor on the IMAX pin, and a programmed start delay can be achieved by driving the shutdown with an open collector/drain device into an R-C network.

PL

This pin's feature ensures that the average MOSFET power dissipation is controlled. A resistor is connected from this pin to the drain of the N-channel MOSFET pass element. When the voltage across the N-channel MOSFET exceeds 5 V, current flows into the PL pin which adds to the fault timer charge current, reducing the duty cycle from the 3% level. When I_{PL} is much greater 36 μA , then the average MOSFET power dissipation is given by:

$$P_{\text{FET(avg)}} = \text{IMAX} \times 1 \times 10^{-6} \times R_{\text{PL}} \tag{4}$$

SENSE

Input voltage from the current sense resistor. When there is greater than 50 mV across this pin with respect to VSS, a fault is sensed, and C_T starts to charge.

DETAILED PIN DESCRIPTIONS (continued)

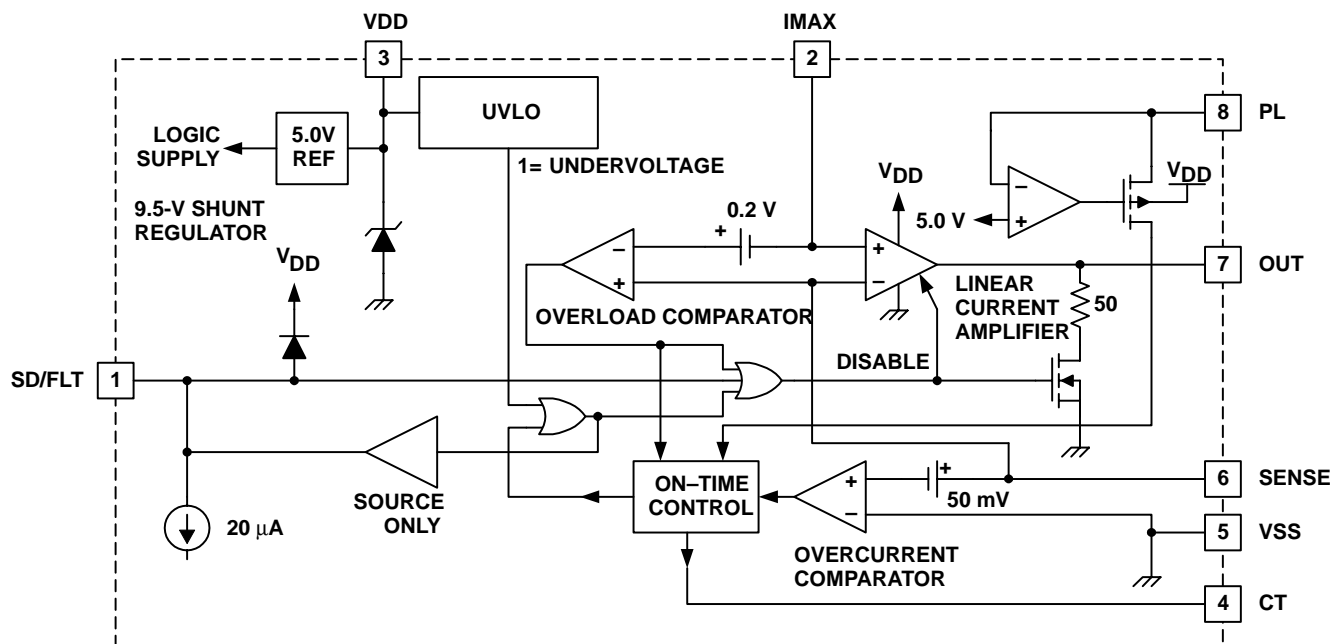
SD/FLT

This pin provides fault output indication and shutdown control. Interface into and out of this pin is usually performed through level shift transistors. When 20 μA is sourced into this pin, shutdown drives high causing the output to disable the N-channel MOSFET pass device. When opened, and under a non-fault condition, the SD/FLT pin pulls to a low state. When a fault is detected by the fault timer, or undervoltage lockout, this pin drives to a high state, indicating the output MOSFET is off.

VDD

Current driven with a resistor to a voltage at least 10-V more positive than VSS. Typically a resistor is connected to ground. The 10-V shunt regulator clamps VDD at 10 V above the VSS pin, and is also used as an output reference to program the maximum allowable sourcing current.

BLOCK DIAGRAM



UDG-99001

APPLICATION INFORMATION

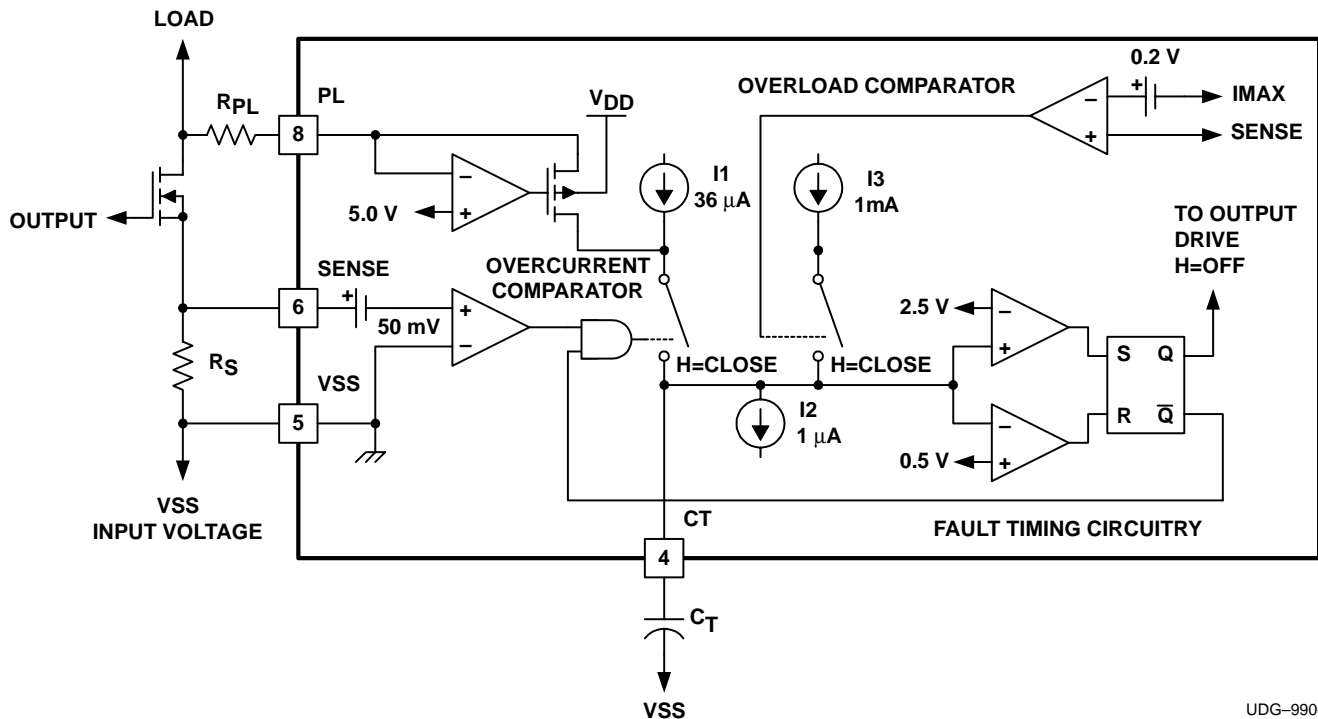
Typical Fault Mode

Figure 1 shows the detailed circuitry for the fault timing function of the UCCx913. This initial discussion of the typical fault mode ignores the overload comparator, and current source I3. Once the voltage across the current sense resistor, R_S , exceeds 50 mV, a fault has occurred. This causes the timing capacitor to charge with a combination of 36 μA plus the current from the power limiting amplifier. The PL amplifier is designed to source current into the CT pin only and to begin sourcing current once the voltage across the output FET exceeds 5 V. The current I_{PL} is related to the voltage across the FET with the following expression:

$$I_{PL} = \frac{V_{FET} - 5\text{ V}}{R_{PL}} \tag{5}$$

where V_{FET} is the voltage across the N-channel MOSFET pass device.

(How this feature limits average power dissipation in the pass device is described in further detail in the following sections). Note that under a condition where the output current is more than the fault level, but less than the maximum level, $V_{OUT} \approx V_{SS}$ (input voltage), $I_{PL} = 0$, the C_T charging current is 36 μA .



UDG-99004

Figure 1. Fault Timing Circuitry Including Power Limit and Overload Comparator

APPLICATION INFORMATION

During a fault, C_T charges at a rate determined by the internal charging current and the external timing capacitor. Once C_T charges to 2.5 V, the fault comparator switches and sets the fault latch. Setting of the fault latch causes both the output to switch off and the charging switch to open. C_T must now discharge with the 1- μ A current source, I_2 , until 0.5 V is reached. Once the voltage at CT reaches 0.5 V, the fault latch resets, which re-enables the output and allows the fault circuitry to regain control of the charging switch. If a fault is still present, the fault comparator closes the charging switch causing the cycle to begin. Under a constant fault, the duty cycle is given by:

$$\text{Duty Cycle} = \frac{1 \mu\text{A}}{I_{\text{PL}} + 36 \mu\text{A}} \quad (6)$$

Average power dissipation in the pass element is given by:

$$P_{\text{FET(avg)}} = V_{\text{FET}} \times I_{\text{MAX}} \times \left(\frac{1 \mu\text{A}}{I_{\text{PL}} + 36 \mu\text{A}} \right) \quad (7)$$

Where $V_{\text{FET}} \gg 5 \text{ V}$ I_{PL} can be approximated as :

$$I_{\text{PL}} \cong \frac{V_{\text{FET}}}{R_{\text{PL}}} \quad (8)$$

and where $I_{\text{PL}} \gg 36 \mu\text{A}$, the duty cycle can be approximated as :

$$\text{Duty Cycle} = \frac{1 \mu\text{A} \times R_{\text{PL}}}{V_{\text{FET}}} \quad (9)$$

Therefore, the maximum average power dissipation in the MOSFET can be approximated by:

$$P_{\text{FET(avg)}} = V_{\text{FET}} \times I_{\text{MAX}} \times \left(\frac{1 \mu\text{A} \times R_{\text{PL}}}{V_{\text{FET}}} \right) = I_{\text{MAX}} \times 1 \mu\text{A} \times R_{\text{PL}} \quad (10)$$

Notice that in the approximation, V_{FET} cancels. therefore, average power dissipation is limited in the N-channel MOSFET pass element.

Overload Comparator

The linear amplifier in the UCCx913 ensures that the output N-channel MOSFET does not pass more than I_{MAX} (which is $V_{\text{IMAX}}/R_{\text{S}}$). In the event the output current exceeds the programmed I_{MAX} by $0.2 \text{ V}/R_{\text{S}}$ (which can only occur if the output MOSFET is not responding to a command from the device) the CT pin begins charging with I_3 , 1 mA, and continue to charge to approximately 8 V. This allows a constant fault to show up on the SD/FLT pin, and also since the voltage on CT charges past 2.5 V only in an overload fault mode, it can be used for detection of output FET failure or to build in redundancy in the system.

APPLICATION INFORMATION

Determining External Component Values (See Figure 2)

To set R_{VDD} the following must be achieved:

$$\frac{V_{IN(min)}}{R_{VDD}} > \frac{10\text{ V}}{(R1 + R2)} + 2\text{ mA} \tag{11}$$

In order to estimate the minimum timing capacitor, C_T , several things must be taken into account. For example, given the schematic below as a possible (and at this point, a standard) application, certain external component values must be known in order to estimate $C_{T(min)}$.

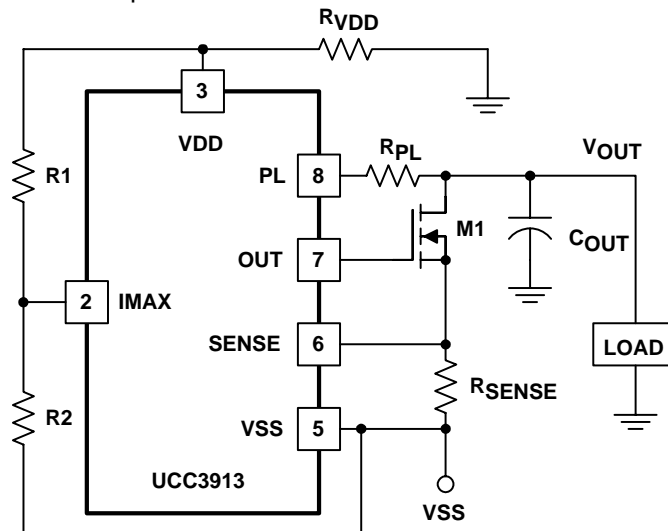
Then use the given the values of C_{OUT} , Load, R_{SENSE} , V_{SS} , and the resistors determining the voltage on the IMAX pin, to calculate the approximate startup time of the node V_{OUT} . This startup time must be faster than the time it takes for C_T to charge to 2.5 V (relative to V_{SS}), and is the basis for estimating the minimum value of C_T . In order to determine the value of the sense resistor, R_{SENSE} , assuming the user has determined the fault current, R_{SENSE} can be calculated by:

$$R_{SENSE} = \frac{50\text{ mV}}{I_{FAULT}} \tag{12}$$

Next, calculate the variable I_{MAX} . I_{MAX} is the maximum current that the device allows through the transistor, M1, and during startup with an output capacitor the power MOSFET, M1, can be modeled as a constant current source of value I_{MAX} where:

$$I_{MAX} = \frac{V_{IMAX}}{R_{SENSE}} \tag{13}$$

where V_{IMAX} = voltage on IMAX pin.



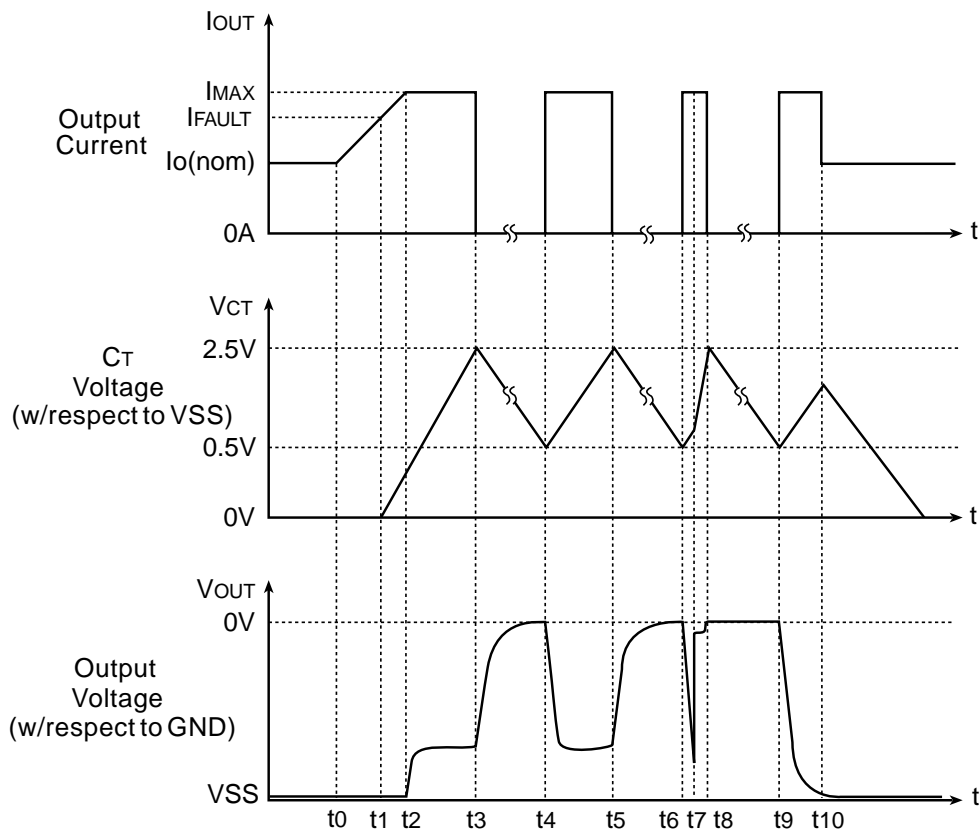
Note: LOAD = I_{LOAD} For Current Source Load
LOAD = R_{OUT} For Resistive Load

UDG-03045

Figure 2. External Component Connections

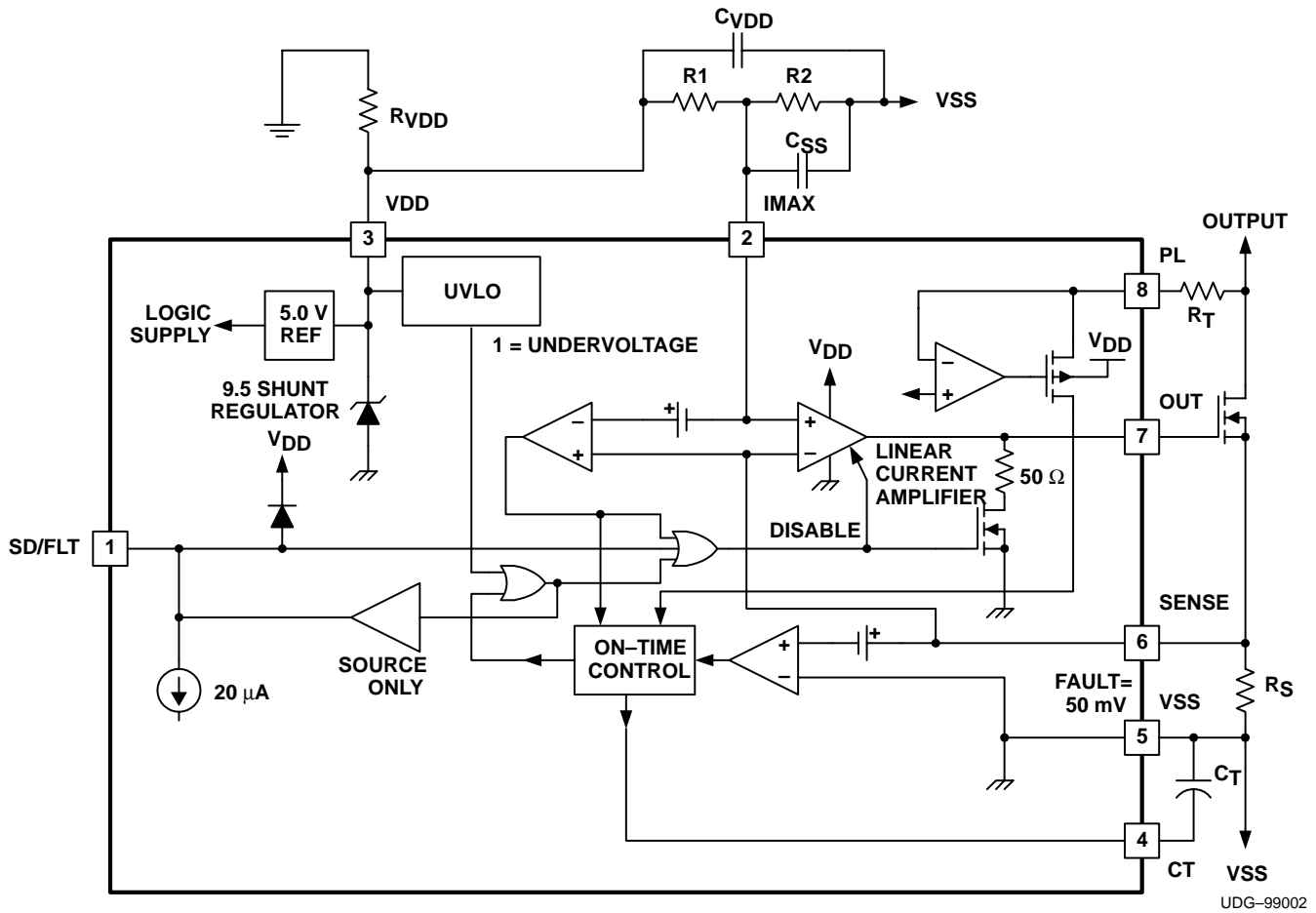
APPLICATION INFORMATION

TIMING DIAGRAM



TIME	DESCRIPTION
t0	Safe condition. Output current is nominal, output voltage is at the negative rail, V _{SS} .
t1	Fault control reached. Output current reaches the programmed fault value. C _T begins to charge at approximately 36-μA.
t2	Maximum current reached. Output current reaches the programmed maximum level and becomes a constant current with value I _{MAX} .
t3	Fault occurs. C _T has charged to 2.5V. Fault output goes high. The FET turns off allowing no output current to flow. V _{OUT} floats up to ground.
t4	Retry. C _T has discharged to 0.5 V, but fault current is still exceeded, C _T begins charging again, FET is on, V _{OUT} pulled down to V _{SS} .
t5	t5 = t3. Illustrates 3% duty cycle.
t6	t6 = t4
t7	Output short circuit. If V _{OUT} is short circuited to ground, C _T charges at a higher rate depending upon the values for V _{SS} and R _{PL} .
t8	Fault occurs. Output is still short circuited, but the occurrence of a fault turns the FET off so no current is conducted.
t9	t9 = t4. Output short circuit released, still in fault mode.
t10	t10 = t0. Fault released. Safe condition. Return to normal operation of the circuit breaker.

APPLICATION INFORMATION



UDG-99002

Figure 3. Typical Application Diagram

To calculate the startup time using the current source load.

$$t_{START} = \frac{C_{OUT} \times |VSS|}{I_{MAX} - I_{LOAD}} \tag{14}$$

To calculate the startup time using the resistive load.

$$t_{START} = C_{OUT} \times R_{OUT} \times \ln \left(\frac{I_{MAX} \times R_{OUT}}{I_{MAX} \times R_{OUT} - |VSS|} \right) \tag{15}$$

APPLICATION INFORMATION

Once t_{START} is calculated, the power limit feature of the UCCx913 must be addressed and component values derived. Assuming the designer chooses to limit the maximum allowable average power that is associated with the circuit breaker, the power limiting resistor, R_{PL} , can be easily determined by the following:

$$R_{PL} = \frac{P_{FET(avg)}}{1 \mu A \times I_{MAX}} \tag{16}$$

where a minimum R_{PL} exists defined by

$$R_{PL(min)} = \frac{|VSS|}{10mA} \tag{17}$$

Finally, after computing the aforementioned variables, the minimum timing capacitor can be derived for a current source load with the following equation.

$$C_{T(min)} = \frac{t_{START} \times (98 \mu A \times R_{PL} + |VSS| - 10 V)}{4 V \times R_{PL}} \tag{18}$$

The minimum timing capacitor can be derived for a resistive load with the following equation.

$$C_{T(min)} = \frac{t_{START} \times (49 \mu A \times R_{PL} + |VSS| - 5 V - I_{MAX} \times R_{OUT}) + R_{OUT} \times C_{OUT} \times |VSS|}{2 V \times R_{PL}} \tag{19}$$

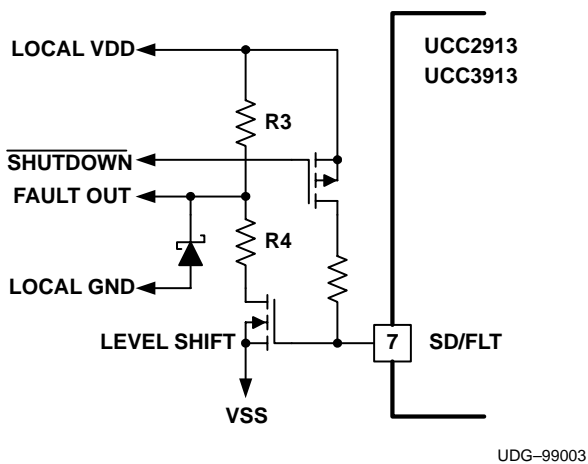


Figure 4. Possible Level Shift Circuitry Interface

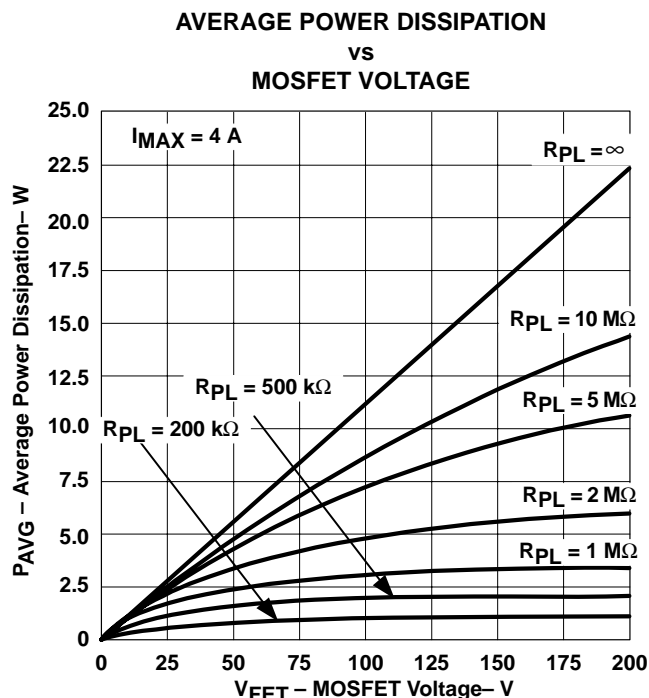


Figure 5

UCC2913 UCC3913

SLUS274A – JANUARY 1999 – REVISED APRIL 2003

SAFETY RECOMMENDATION

Although the UCC3913 is designed to provide system protection for all fault conditions, all integrated circuits can ultimately fail short. For this reason, if the UCC3913 is intended for use in safety critical applications where UL or some other safety rating is required, a redundant safety device such as a fuse should be placed in series with the device. The UCC3913 will prevent the fuse from blowing for virtually all fault conditions, increasing system reliability and reducing maintenance cost, in addition to providing the hot swap benefits of the device.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCC2913D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2913	Samples
UCC2913DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2913	Samples
UCC2913DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2913	Samples
UCC2913DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2913	Samples
UCC2913J	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-40 to 85		
UCC2913N	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI	-40 to 85	UCC2913N	
UCC3913D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3913	Samples
UCC3913DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3913	Samples
UCC3913DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3913	Samples
UCC3913DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3913	Samples
UCC3913N	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI	0 to 70	UCC3913N	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC2913DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC3913DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

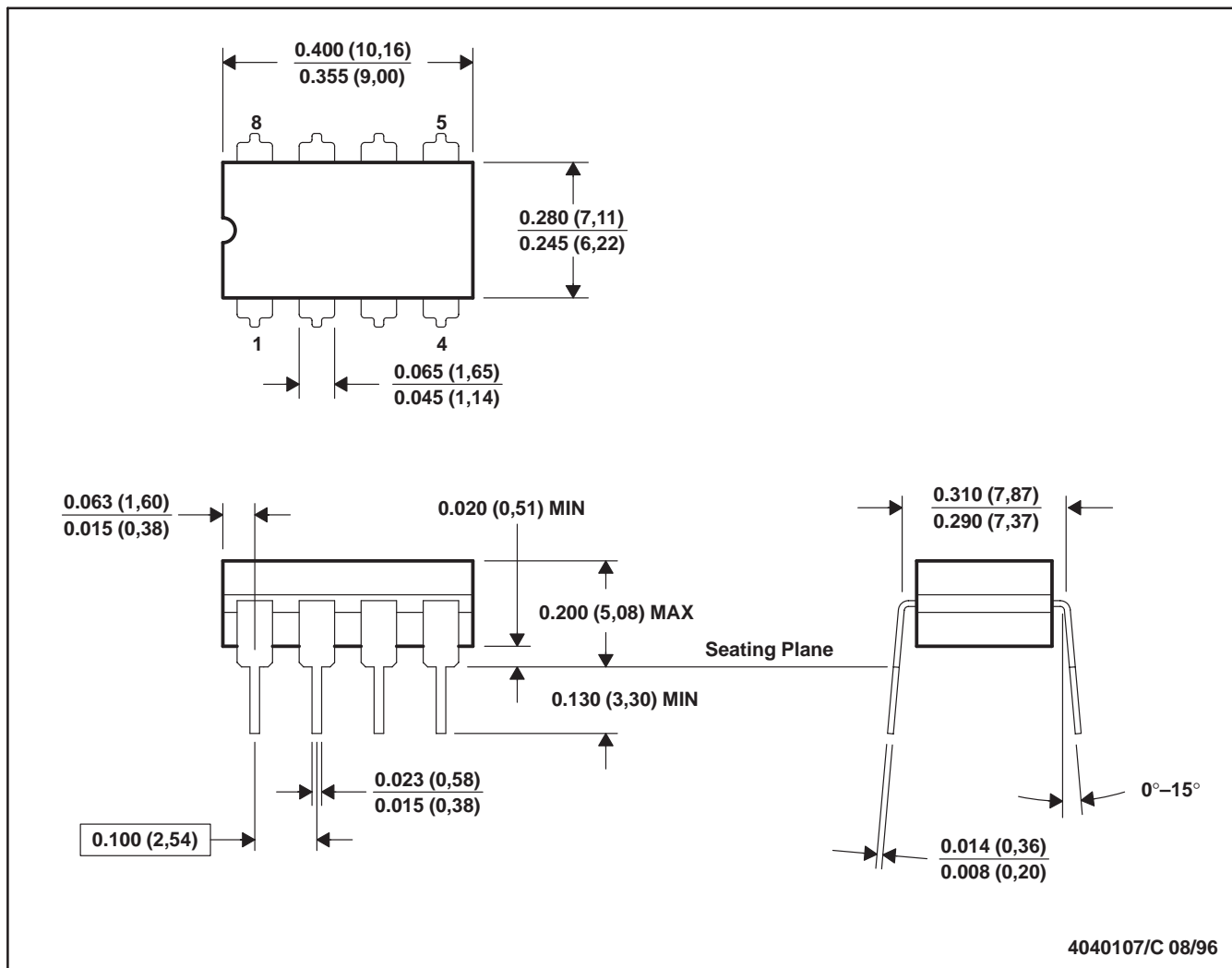
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC2913DTR	SOIC	D	8	2500	367.0	367.0	35.0
UCC3913DTR	SOIC	D	8	2500	367.0	367.0	35.0

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP1-T8

P (R-PDIP-T8)

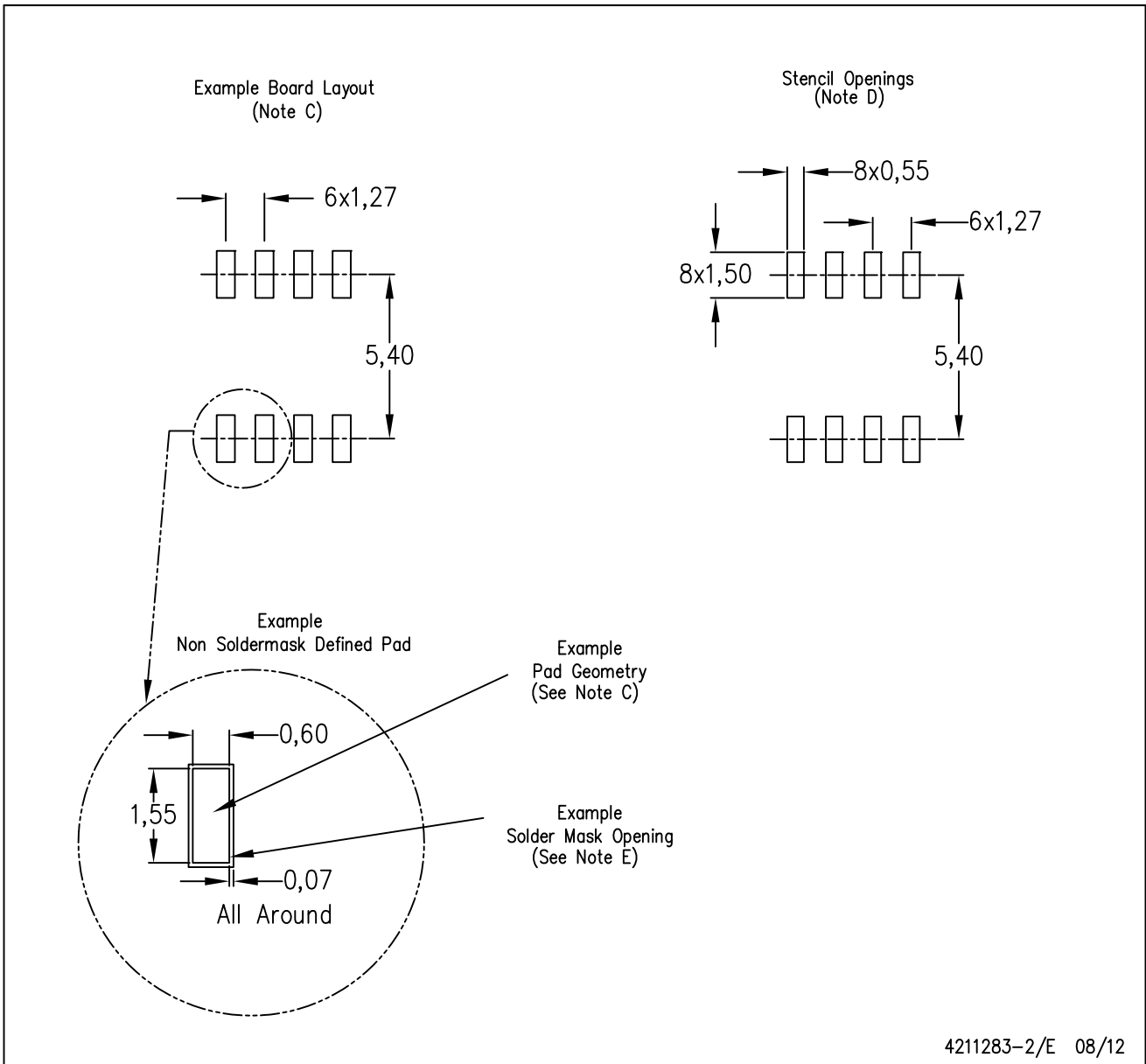
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com